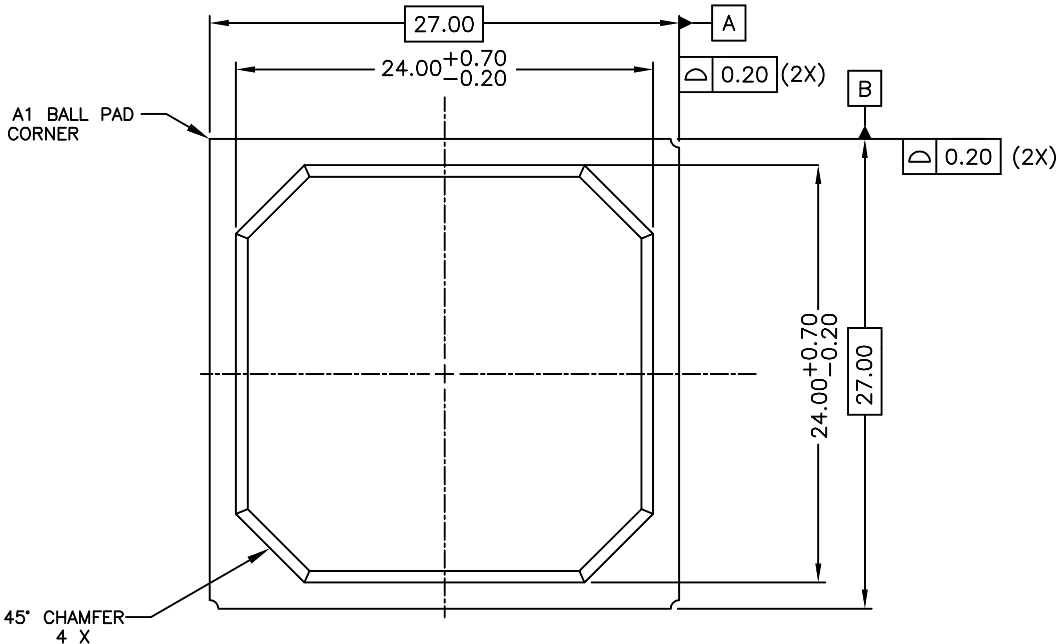
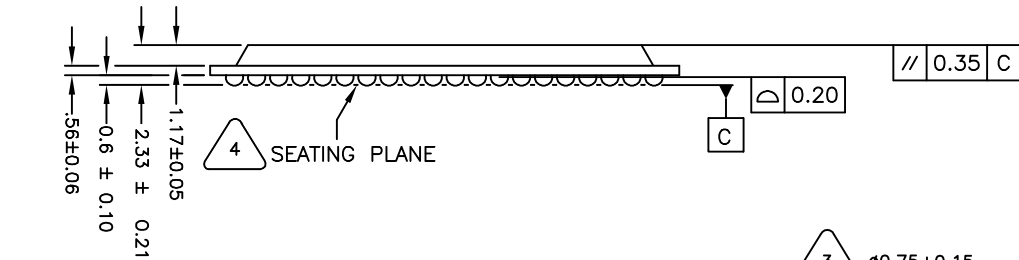
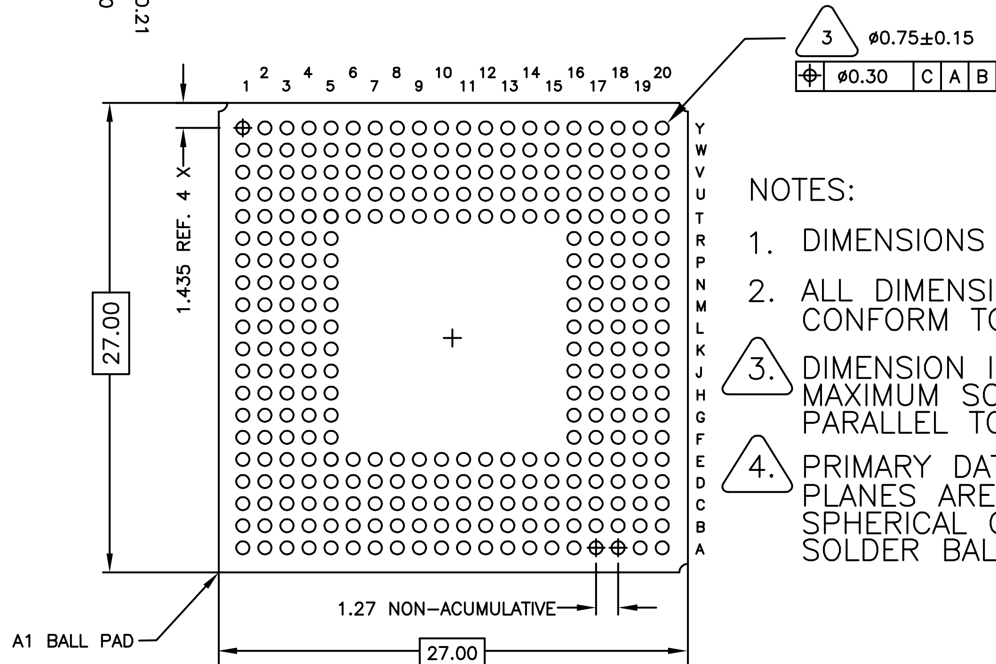
LTR.	DESCRIPTION	DATE	APPROVED
A	NEW DRAWING	2/98	
B	REVISE DWG PER ECN #25019	3/00	
C	REVISE DWG PER ECN #42279	10/04	







NOTES:

1. DIMENSIONS ARE IN MILLIMETERS
2. ALL DIMENSIONS AND TOLERANCE CONFORM TO ASME Y 14.5M−1994
3. DIMENSION IS MEASURED AT THE MAXIMUM SOLDER BALL DIAMETER, PARALLEL TO PRIMARY DATUM C
4. PRIMARY DATUM C AND SEATING PLANES ARE DEFINED BY THE SPHERICAL CROWNS OF THE SOLDER BALLS.

SIGNATURE		DATE
DOC. CONTROL:		
ENGR. MGR:		
MFG. ENGR:		
CHECKED BY:	TWM	10/04
DRAWN BY:	JFD	10/04

DALLAS SEMICONDUCTOR MAXIM

TITLE: MARKETING OUTLINE, 300 LEAD, PBGA (27X27) 1.27 MM PITCH, 2.33 MM THICK, 4 LAYER

SIZE	FSCM NO.	PART NO.	REV.
A		56-G6003-001	C

SCALE	N/A	SHEET	1 of 1